

***IN THE UNITED STATES PATENT AND TRADEMARK OFFICE***

Applicant: Lopatin et al.

Title: METHOD OF USING TERNARY COPPER ALLOY TO  
OBTAIN A LOW RESISTANCE AND LARGE GRAIN SIZE  
INTERCONNECT

Appl. No.: 09/994,395

Filing Date: 11/26/2001

Examiner: Ori Nadav

Art Unit: 2811

Confirmation Number: 7882

**AMENDMENT AND REPLY UNDER 37 CFR 1.116**

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

This communication is responsive to the Decision on Appeal, dated January 27, 2009, concerning the above-referenced patent application.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this document.

**Remarks/Arguments** begin on page 6 of this document.

Please amend the application as follows: